



A 级覆铜板质量技术指标(Class A)

Treat Item	Treatment Condition	SPEC	Typical Value
1. Peel Strength Pound/inch, Minimum A 1/2 oz cooper Incept 接收状态 Thermal stress 热应力 提高温度下 暴露于工艺溶液后 B 1oz copper 盎司铜箔 Incept 接收状态 Thermal stress 热应力 提高温度下 暴露于工艺溶液后	A A 125°C 125°C A A 125°C 125°C	≥6.0 ≥6.0 ≥4.0 ≥4.5 ≥8.0 ≥8.0 ≥6.0 ≥7.0	6.0-8.0 6.0-8.0 7.0 7.0 8.0-10.0 8.0-10.0 9.0 9.0
2. Volume resistivity, Mix, MΩ.CM 在提高温度下	E-24/125	≥10 ³	10 ⁶
3. Surface resistance, Minimum, 在提高温度下	E-24/125	≥10 ³	10 ⁶
4. Water absorption, Max(%)	E-1/105+des	≤0.80	0.18-0.35
5. Breakdown Pressure, Mix(KV), 步进(厚度 ≥ 0.50 mm)	D-48/50 D-0.5/23	≥35	38
6. Flexural Strength, Mix(N/mm ²) (thickness ≥ 0.50 mm) LW CW	A A	≥415 ≥345	495 405
7. ARC Resistance, Mix, secs.	D-48/50 D-0.5/23	≥60	75
8. Flame retardant 阻燃性	A	UL94V0	UL94V0
9. Solderability 可焊性	A	Solderability	Solderability
10. Dielectric constant, 1MHZ	A	≤ 5.4	4.7-4.8
11. Dissipation Factor, 1MHZ	A	≤0.045	0.020-0.035
12. Flexural, Max(%) Double side(Thickness>0.78mm ; Size:300mm × 300mm) Single side (Thickness>0.78mm ; Size:300mm × 300mm) Double side (Thickness:0.5~0.78 mm; Size:300mm× 300mm) Single side (Thickness:0.5~0.78 mm; Size:300mm× 300mm)	A A A A	≤1.0 ≤1.5 ≤1.5 ≤2.0	0.20-0.50 0.30-0.70 0.30-0.50 0.35-0.70
13. Thermal stress, 288°C, Solder dip 10Secs. Unetched	A	NO DEFECT	55-80 Sec
14. 玻璃化转变温度, TG(DSC, °C)	A	≥125	135
15. CTI 本项目仅供参考	等级为 ≤3 (175-250)		